TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

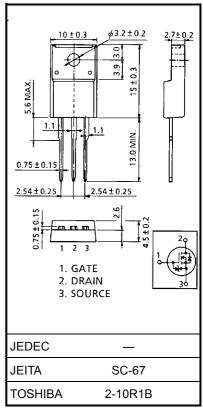
2SK2543

Switching Regulator Applications

- Low drain-source ON resistance $: R_{DS} (ON) = 0.75 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 7.0 \text{ S (typ.)}$
- Low leakage current $: IDSS = 100 \ \mu A \ (max) \ (VDS = 500 \ V)$
- Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	500	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V _{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	8	А	
	Pulse (Note 1)	I _{DP}	32	А	
Drain power dissipatio	n (Tc = 25°C)	PD	40	W	
Single pulse avalanche energy (Note 2)		E _{AS}	312	mJ	
Avalanche current		I _{AR}	8	А	
Repetitive avalanche	energy (Note 3)	E _{AR}	4	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature r	ange	T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	3.125	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 8.3 mH, R_G = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution. Unit: mm

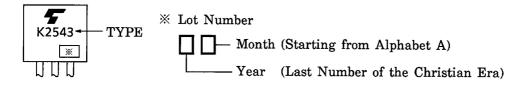
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V_{GS} = ±25 V, V_{DS} = 0 V	_		±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I_{G} = ±10 µA, V_{GS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 500 V, V _{DS} = 0 V			100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500			V
Gate threshold v	/oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0		4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A		0.75	0.85	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 4 A	3.5	7.0	_	S
Input capacitance	e	C _{iss}			1300	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	130	_	
Output capacitance		C _{oss}			400		
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{}_{0 \text{ V}} \int I_{D} = 4 \text{ A}$ $V_{GS} \stackrel{0 \text{ V}}{}_{0 \text{ V}} \int I_{D} = 50 \Omega$ $V_{DD} = 200 \text{ V}$		26		
	Turn-on time	t _{on}		_	45	_	ne
	Fall time	t _f		_	40		ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w = 10 µs	_	140	-	
Total gate charge (Gate-source plus gate-drain)		Qg		_	30	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 8 A		17	—	nC
Gate-drain ("miller") charge		Q _{gd}			13	—	

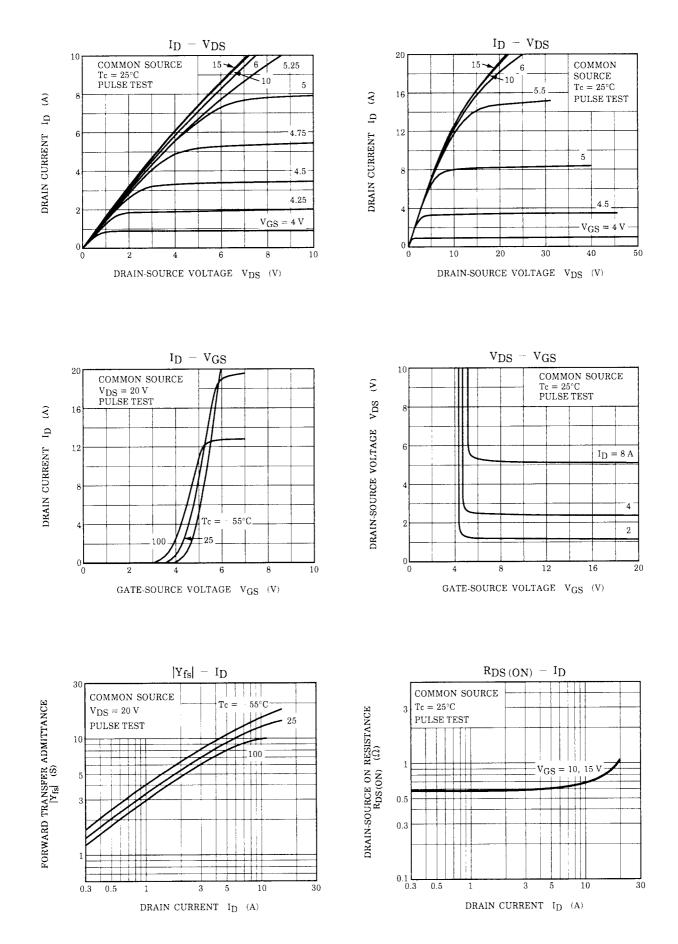
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	8	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	32	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 8 A, V _{GS} = 0 V			-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 8 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs		1200		ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / μs		10		μC

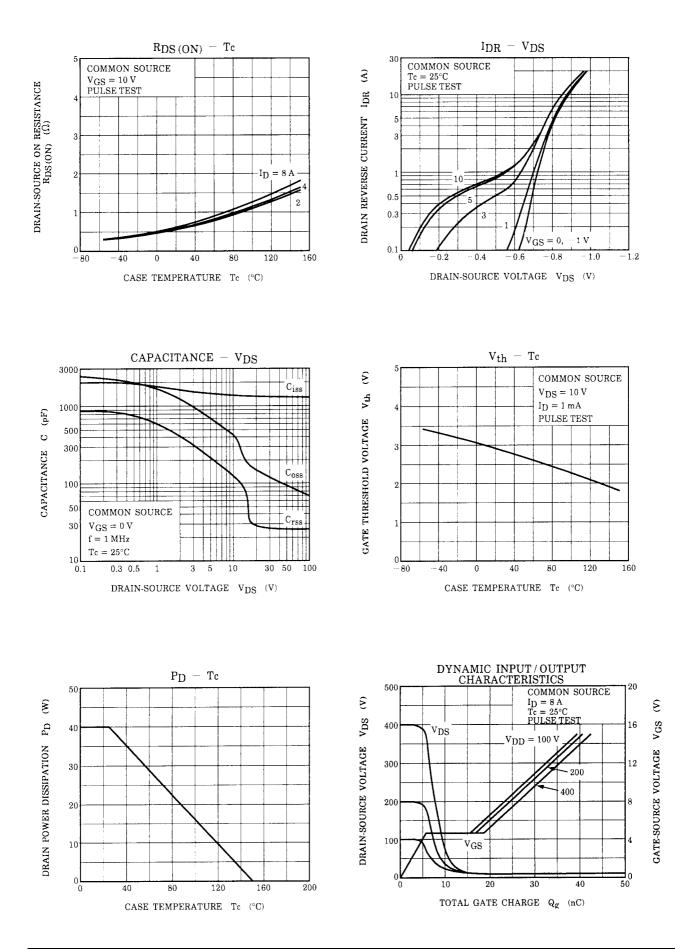
Marking



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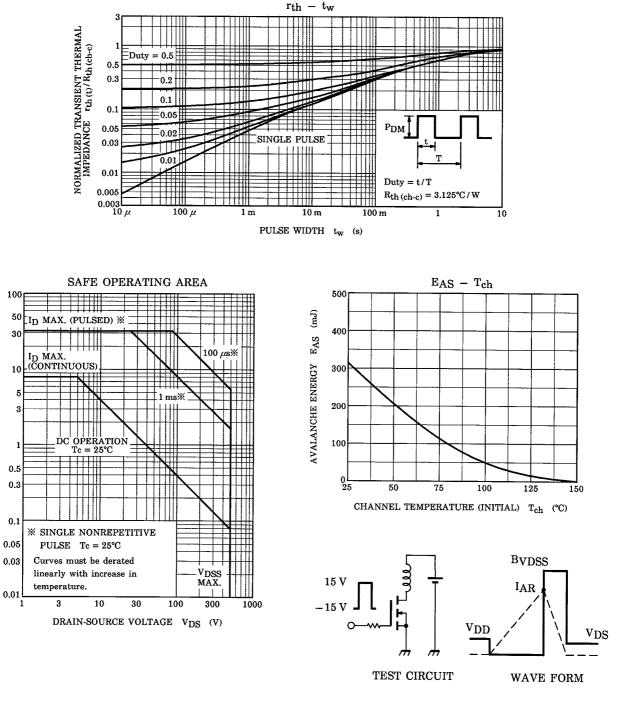


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DRAIN CURRENT ID



 $\begin{array}{l} \mathrm{RG} = 25 \ \Omega \\ \mathrm{V_{DD}} = 90 \ \mathrm{V}, \ \mathrm{L} = 8.3 \ \mathrm{mH} \end{array} \qquad \mathrm{EAS} = \frac{1}{2} \cdot \mathrm{L} \cdot \mathrm{I}^2 \cdot \left(\frac{\mathrm{BVDSS}}{\mathrm{BVDSS} - \mathrm{VDD}} \right) \end{array}$

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